

**Amendments to the Claims**

This listing of claims will replace all prior listings of claims in the application.

**Listing of Claims**

1. (Previously Presented) An electroless copper plating solution, containing a water-soluble nitrogen-containing polymer and glyoxylic acid and phosphinic acid as reducing agents in the electroless copper plating solution.

2. (Original) An electroless copper plating solution according to Claim 1, wherein the water-soluble nitrogen-containing polymer is a polyacrylamide or a polyethyleneimine.

3. (Previously Presented) An electroless copper plating solution according to Claim 1, wherein a weight average molecular weight (Mw) of the water-soluble nitrogen-containing polymer is at least 100,000, and Mw/Mn (Mn is a number average molecular weight thereof) is 10.0 or less.

4. (Canceled)

5. (Previously Presented) In an electroless copper plating method for depositing a copper plating on a substrate, the improvement comprising performing the electroless copper plating with the electroless copper plating solution according to Claim 1.

6. (New) An electroless copper plating solution, containing a polyacrylamide and glyoxylic acid and phosphinic acid as reducing agents in the electroless copper plating solution.

7. (New) An electroless copper plating solution, containing a polyethyleneimine and glyoxylic acid and phosphinic acid as reducing agents in the electroless copper plating solution.